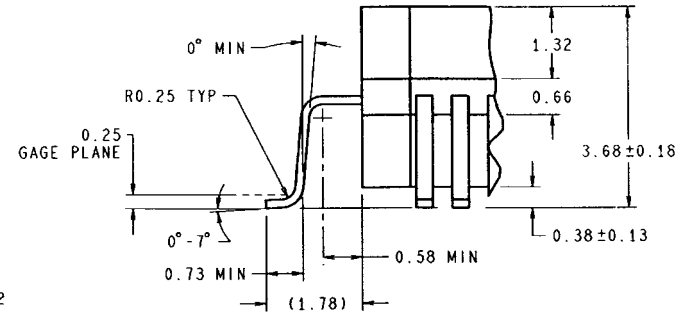
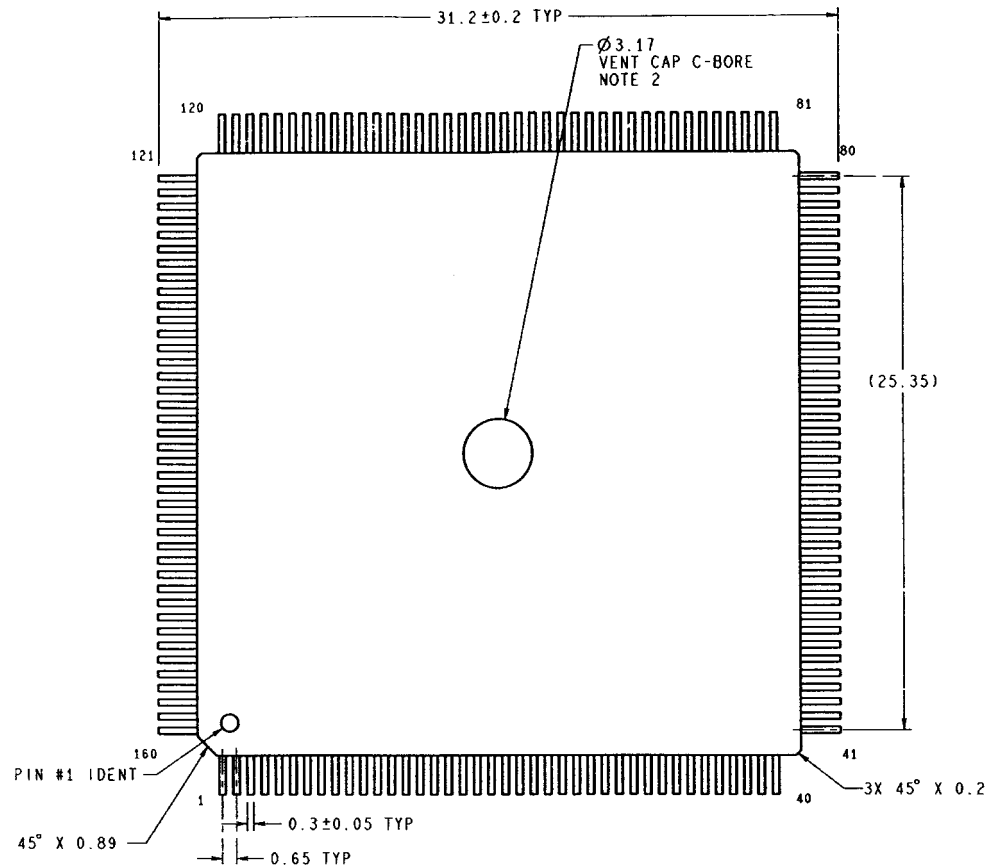
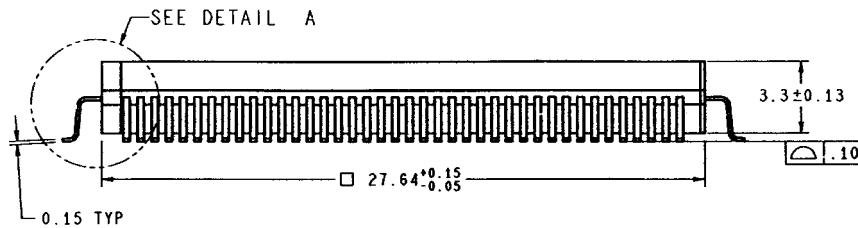


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
B	REVISE AND REDRAW PER NEW STANDARD.	11186	12/12/95	DEG/S.M.



DETAIL A  
TYP. SCALE: 15X  
NOTE 2



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED.

- STANDARD LEAD FINISH: 5.08 MICROMETERS MINIMUM SOLDER PLATING (85/15) THICKNESS.
- THE LEADS CAN BE FORMED FOR CAVITY UP OR DOWN:  
- THE VENT CAP WILL BE ON THE TOP FOR CAVITY UP (SHOWN)  
- THE VENT CAP WILL BE ON THE BOTTOM FOR CAVITY DOWN
- REFERENCE: OLIN DRAWING 04-160-YH-001, REV C, DATED MAY/93

APPROVALS	DATE	National Semiconductor			
DRW: D.E. Grady	12/12/95	2900 Semiconductor Dr., Santa Clara, CA 95052-8090			
DTG. CHK:	1/16/96	MQAD, 28 X 28 X 3.3mm, 160 LEAD			
ENG. CHK:	1/12/96				
PROJECTION		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	MKT-AUL160A	B
DO NOT SCALE DRAWING				SHEET 1 of 1	